Is Now Part of

ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

FAIRCHILD

March 2015

FGA60N60UFD

600 V, 60 A Field Stop IGBT

Features

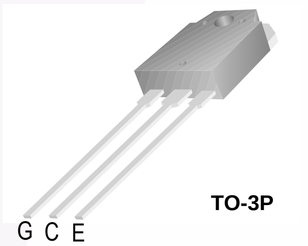
- High Current Capability
- Low Saturation Voltage: $V_{CE(sat)}$ = 1.9 V @ I_C = 60 A
- High Input Impedance
- Fast Switching
- RoHS Compliant

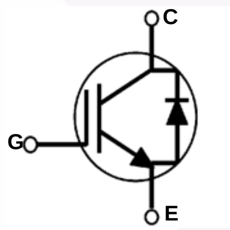
Applications

- Solar Inverter, UPS, Welder, PFC

General Description

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description		Ratings	Unit
V_{CES}	Collector to Emitter Voltage		600	V
V_{GES}	Gate to Emitter Voltage		±20	V
	Transient Gate-to-Emitter Voltage		±30	
I_C	Collector Current	@ T_C = 25°C	120	A
	Collector Current	@ T_C = 100°C	60	A
$I_{CM\ (1)}$	Pulsed Collector Current	@ T_C = 25°C	180	A
P_D	Maximum Power Dissipation	@ T_C = 25°C	298	W
	Maximum Power Dissipation	@ T_C = 100°C	119	W
T_J	Operating Junction Temperature		-55 to +150	°C
T_{stg}	Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:
1: Repetitive test , Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$(IGBT)	Thermal Resistance, Junction to Case	-	0.33	°C/W
$R_{\theta JC}$(Diode)	Thermal Resistance, Junction to Case	-	1.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA60N60UFDTU	FGA60N60UFD	TO-3P	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT

T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{CES}	Collector to Emitter Breakdown Voltage	V_{GE} = 0 V, I_C = 250 μA	600	-	-	V
ΔBV_{CES} / ΔT_J	Temperature Coefficient of Breakdown Voltage	V_{GE} = 0 V, I_C = 250 μA	-	0.67	-	V/°C
I_{CES}	Collector Cut-Off Current	V_{CE} = V_{CES}, V_{GE} = 0 V	-	-	250	μA
I_{GES}	G-E Leakage Current	V_{GE} = V_{GES}, V_{CE} = 0 V	-	-	±400	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	I_C = 250 μA, V_{CE} = V_{GE}	4.0	5.0	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C = 60 A, V_{GE} = 15 V	-	1.9	2.4	V
		I_C = 60 A, V_{GE} = 15 V, T_C = 125°C	-	2.1	-	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	-	2855	-	pF
C_{oes}	Output Capacitance		-	325	-	pF
C_{res}	Reverse Transfer Capacitance		-	110	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 400 V, I_C = 60 A, R_G = 5 Ω, V_{GE} = 15 V, Inductive Load, T_C = 25°C	-	23	-	ns
t_r	Rise Time		-	58	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	130	-	ns
t_f	Fall Time		-	40	80	ns
E_{on}	Turn-On Switching Loss		-	1.81	-	mJ
E_{off}	Turn-Off Switching Loss		-	0.81	-	mJ
E_{ts}	Total Switching Loss		-	2.62	-	mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 400 V, I_C = 60 A, R_G = 5 Ω, V_{GE} = 15 V, Inductive Load, T_C = 125°C	-	22	-	ns
t_r	Rise Time		-	61	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	141	-	ns
t_f	Fall Time		-	63	-	ns
E_{on}	Turn-On Switching Loss		-	1.92	-	mJ
E_{off}	Turn-Off Switching Loss		-	1.23	-	mJ
E_{ts}	Total Switching Loss		-	3.15	-	mJ
Q_g	Total Gate Charge	V_{CE} = 400 V, I_C = 60 A, V_{GE} = 15 V	-	188	-	nC
Q_{ge}	Gate to Emitter Charge		-	21	-	nC
Q_{gc}	Gate to Collector Charge		-	97	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Typ.	Max	Unit
V_{FM}	Diode Forward Voltage	I_F = 30 A	T_C = 25°C	-	2.0	2.6	V
			T_C = 125°C	-	1.8	-	
t_{rr}	Diode Reverse Recovery Time	I_F = 30 A, di_F/dt = 200 A/μs	T_C = 25°C	-	47	-	ns
			T_C = 125°C	-	179	-	
Q_{rr}	Diode Reverse Recovery Charge		T_C = 25°C	-	83	-	nC
			T_C = 125°C	-	567	-	

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

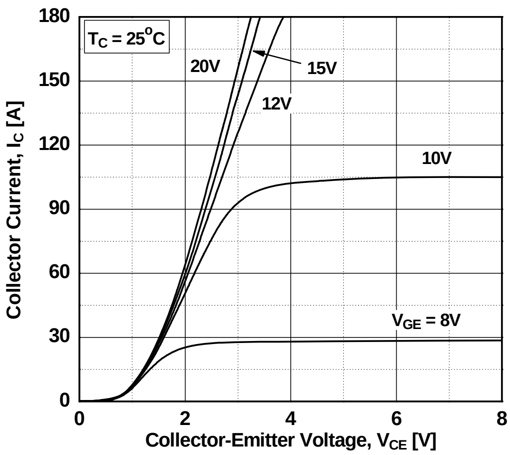


Figure 2. Typical Output Characteristics

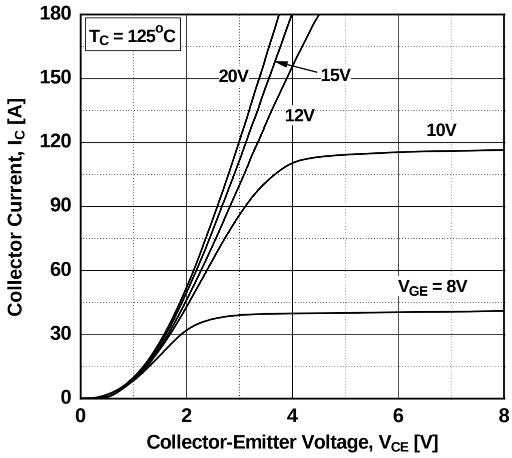


Figure 3. Typical Saturation Voltage Characteristics

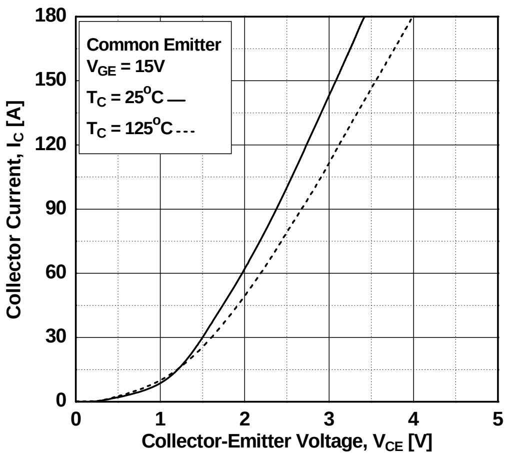


Figure 4. Transfer Characteristics

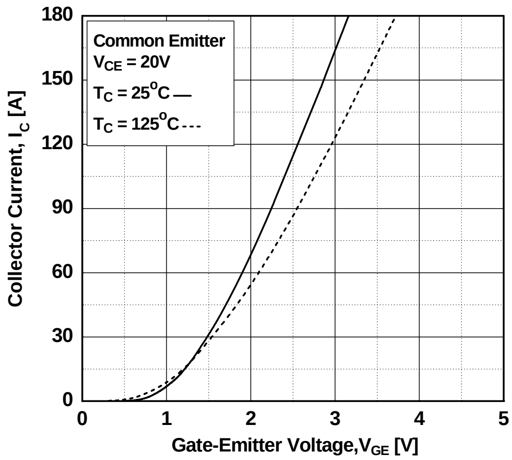


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

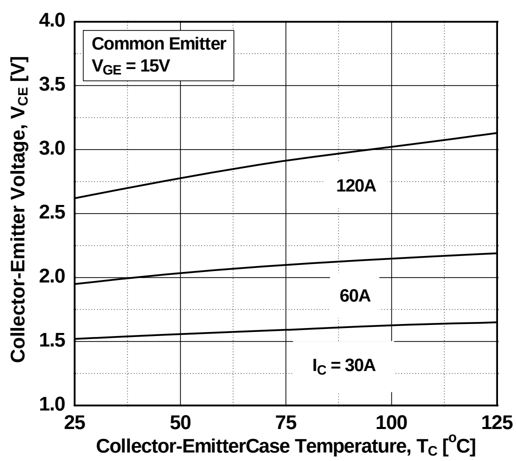
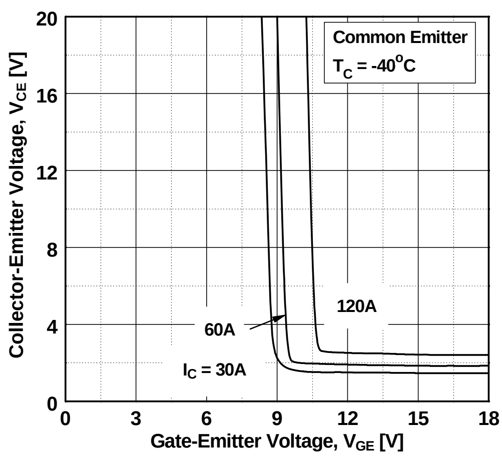


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. V_{GE}

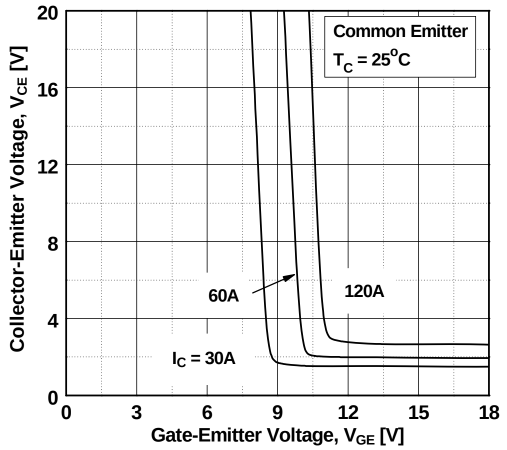


Figure 8. Saturation Voltage vs. V_{GE}

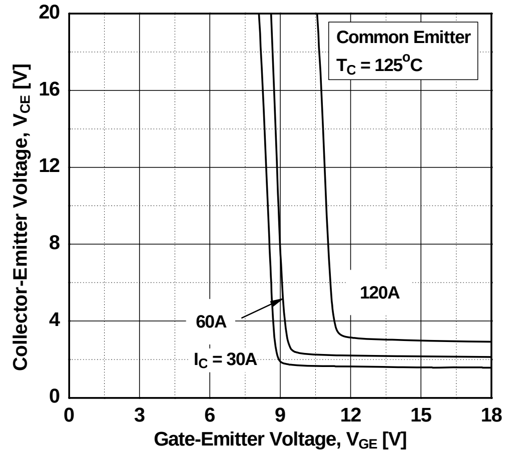


Figure 9. Capacitance Characteristics

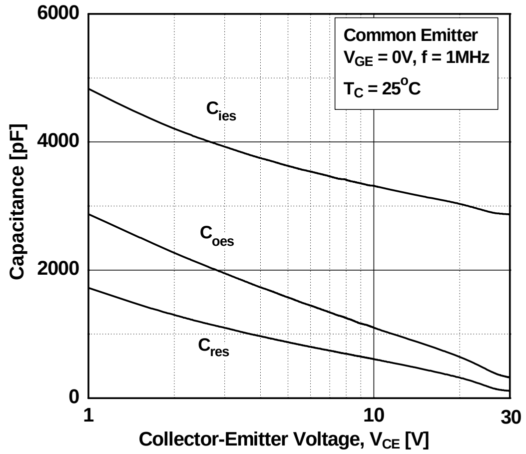


Figure 10. Gate charge Characteristics

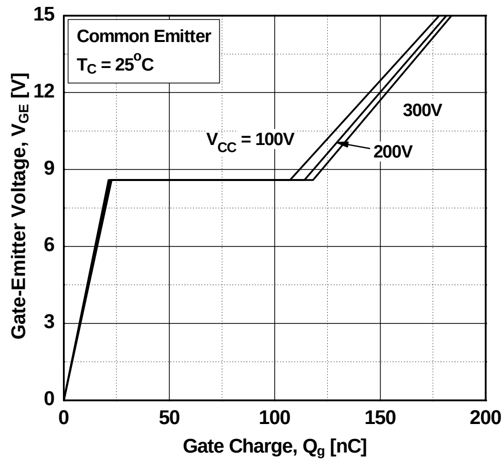


Figure 11. SOA Characteristics

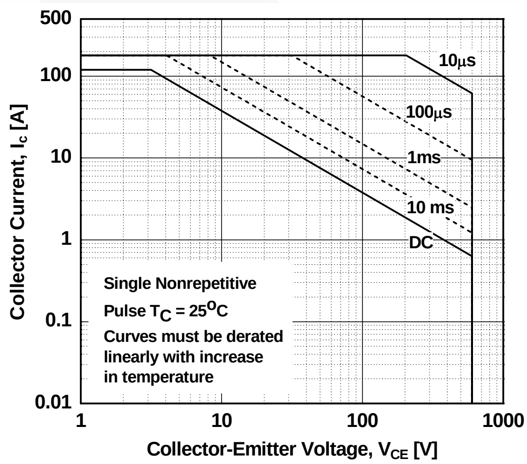
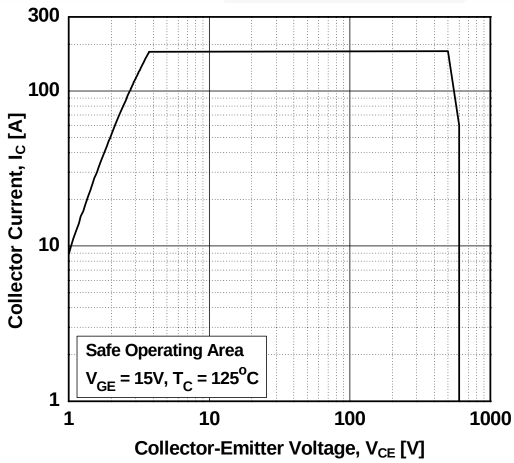


Figure 12. Turn off Switching SOA Characteristics



Typical Performance Characteristics

Figure 13. Turn-on Characteristics vs. Gate Resistance

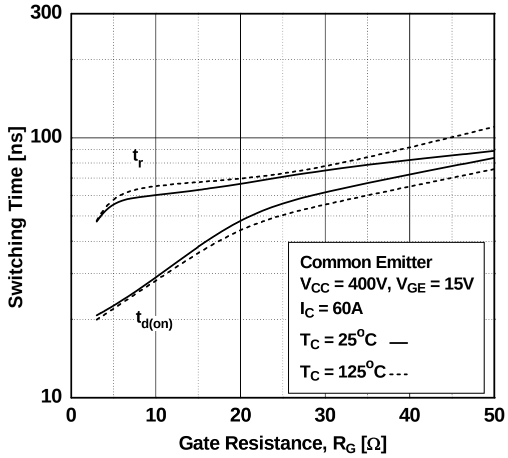


Figure 14. Turn-off Characteristics vs. Gate Resistance

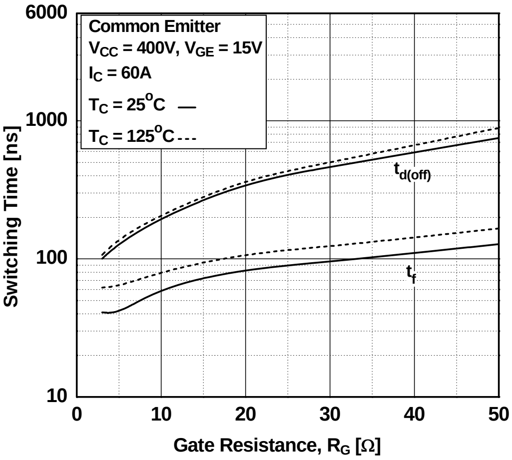


Figure 15. Turn-on Characteristics vs. Collector Current

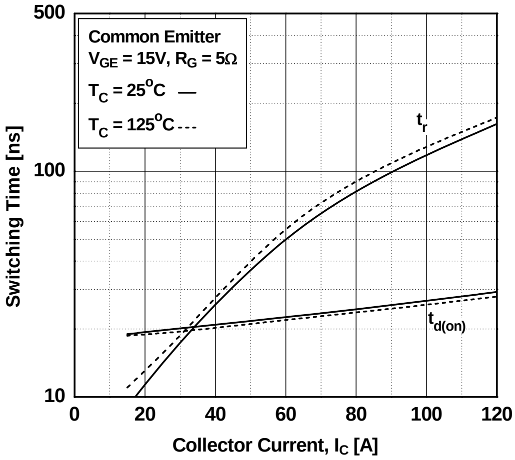


Figure 16. Turn-off Characteristics vs. Collector Current

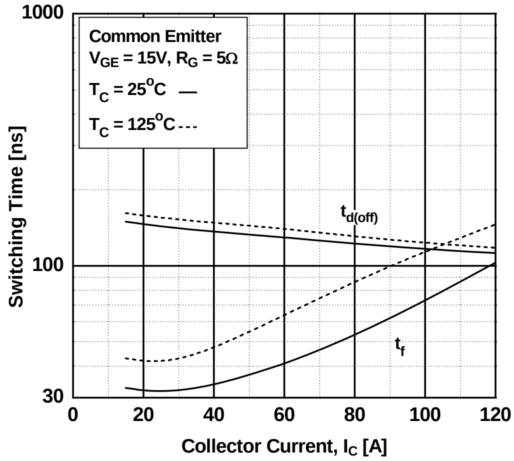


Figure 17. Switching Loss vs. Gate Resistance

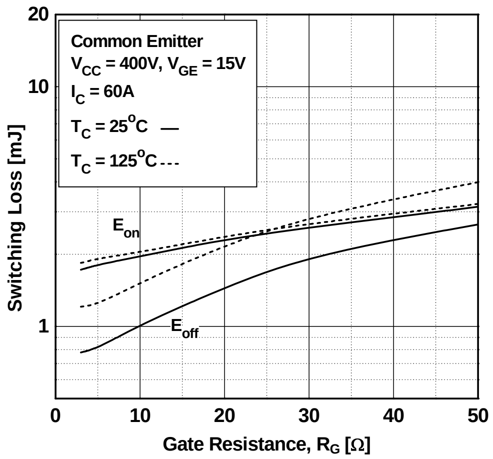
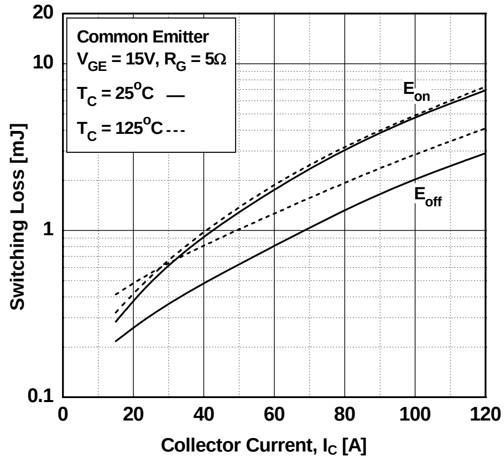


Figure 18. Switching Loss vs. Collector Current



Typical Performance Characteristics

Figure 19. Forward Characteristics

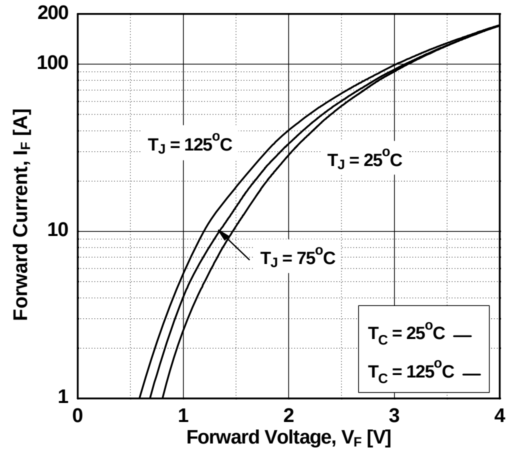


Figure 20. Reverse Current

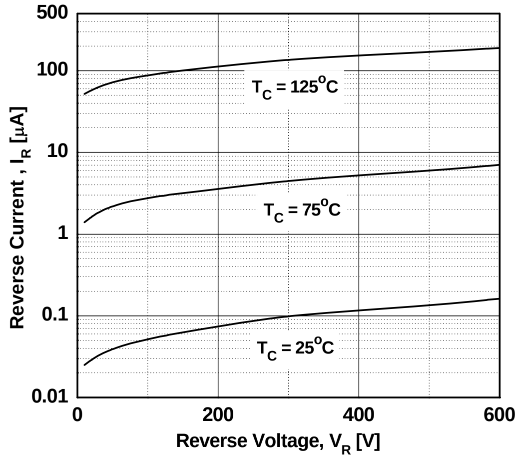


Figure 21. Stored Charge

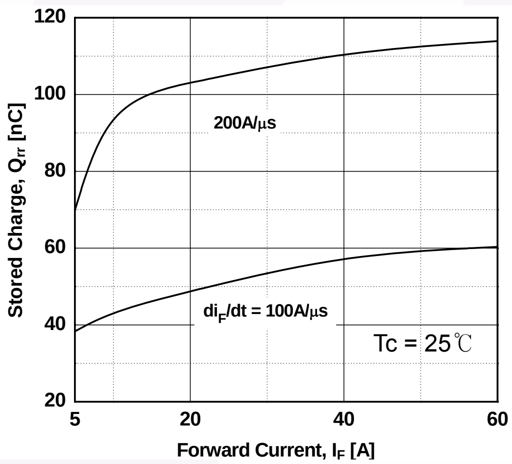


Figure 22. Reverse Recovery Time

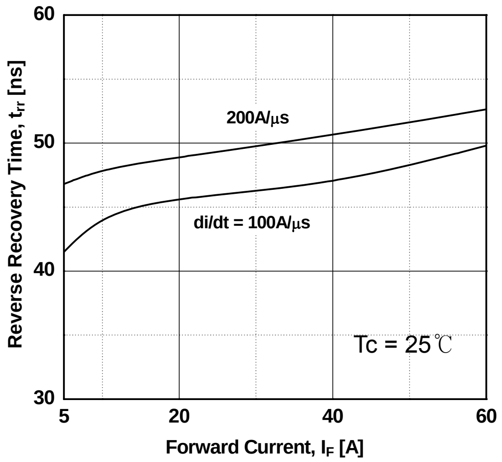
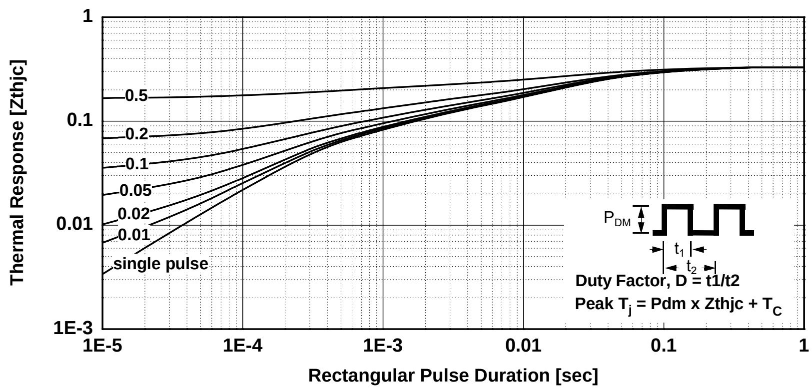
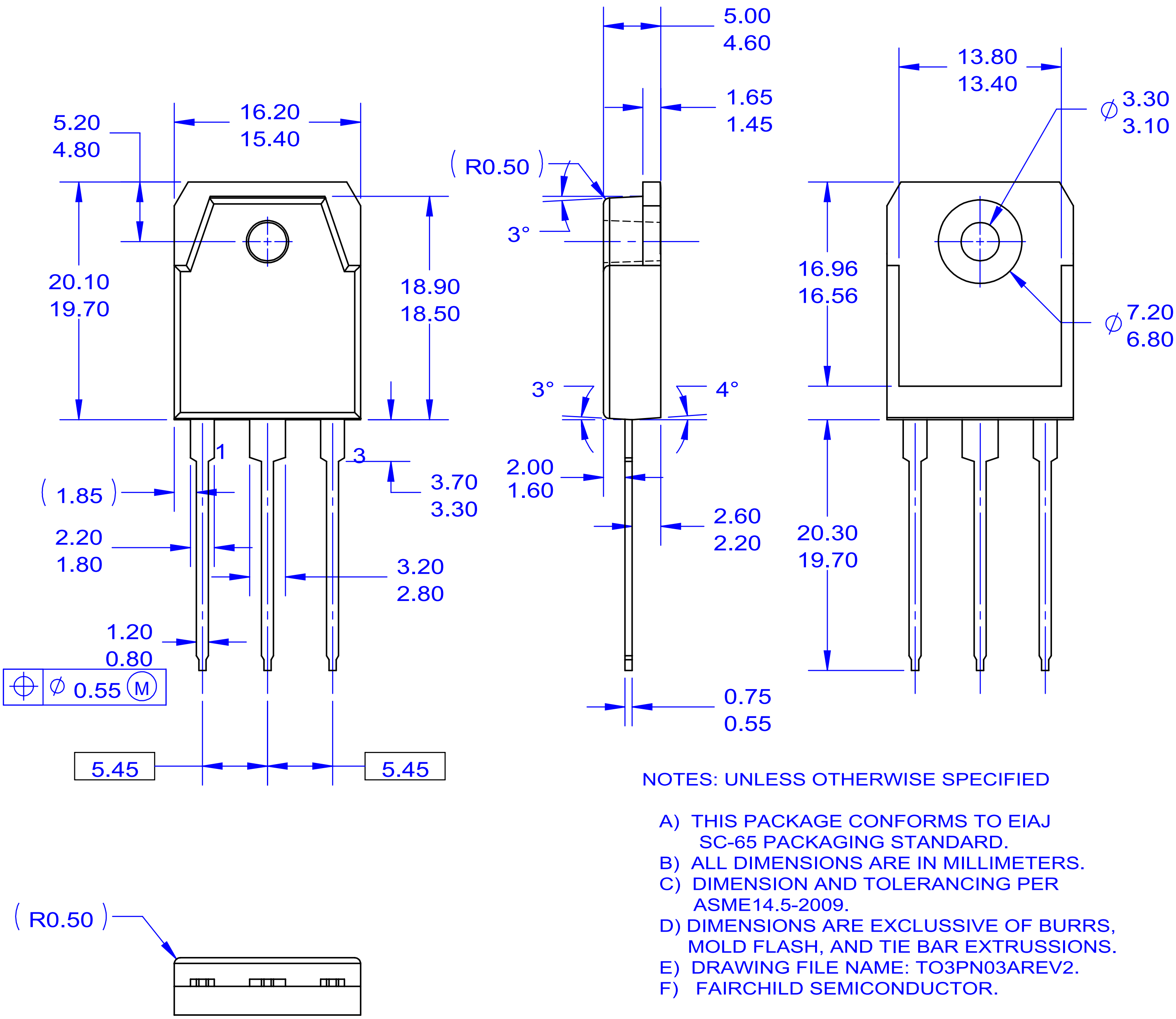


Figure 23. Transient Thermal Impedance of IGBT





NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
E) DRAWING FILE NAME: TO3PN03AREV2.
F) FAIRCHILD SEMICONDUCTOR.

FAIRCHILD ™

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative